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FDS4141

P-Channel PowerTrench[®] MOSFET -40V, -10.8A, 13.0m Ω

Features

- Max $r_{DS(on)} = 13.0 \text{m}\Omega$ at $V_{GS} = -10 \text{V}$, $I_D = -10.5 \text{A}$
- Max $r_{DS(on)} = 19.0 \text{m}\Omega$ at $V_{GS} = -4.5 \text{V}$, $I_D = -8.4 \text{A}$
- High performance trench technology for extremely low r_{DS(on)}
- RoHS Compliant

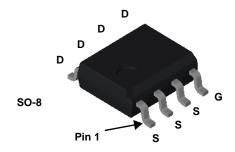


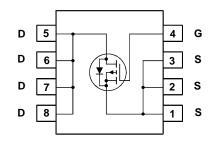
General Description

This P-Channel MOSFET has been produced using On Semiconductor's proprietary PowerTrench® technology to deliver low $r_{DS(on)}$ and optimized BV_{DSS} capability to offer superior performance benefit in the applications and optimized switching performance capability reducing power dissipation losses in converter/inverter applications.

Applications

- Control switch in synchronous & non-synchronous buck
- Load switch
- Inverter





MOSFET Maximum Ratings T_A = 25°C unless otherwise noted

Symbol	Parameter		Ratings	Units	
V _{DS}	Drain to Source Voltage		-40	V	
V_{GS}	Gate to Source Voltage		±20	V	
	Drain Current -Continuous		-10.8	А	
'D	-Pulsed		-36		
E _{AS}	Single Pulse Avalanche Energy	(Note 3)	294	mJ	
Б	Power Dissipation T _A = 25°C	(Note 1a)	5	W	
P_{D}	Power Dissipation T _A = 25°C	(Note 1b)	2.5	VV	
T_J , T_{STG}	Operating and Storage Junction Temperature Range		-55 to +150	°C	

Thermal Characteristics

$R_{\theta JC}$	Thermal Resistance, Junction to Case	(Note 1)	25	°C/M
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient	(Note 1a)	50	°C/W

Package Marking and Ordering Information

Device Marking	Device	Package	Reel Size	Tape Width	Quantity
FDS4141	FDS4141	SO-8	13"	12mm	2500units

Electrical Characteristics $T_J = 25^{\circ}C$ unless otherwise noted **Parameter**

Symbol	Parameter	Test Conditions	Min	Тур	Max	Units
Off Chara	acteristics					
BV _{DSS}	Drain to Source Breakdown Voltage	$I_D = -250 \mu A, V_{GS} = 0 V$	-40			V
$\frac{\Delta BV_{DSS}}{\Delta T_{J}}$	Breakdown Voltage Temperature Coefficient	I _D = -250μA, referenced to 25°C		-33		mV/°C
I _{DSS}	Zero Gate Voltage Drain Current	$V_{DS} = -32V$,			-1	μА
I _{GSS}	Gate to Source Leakage Current	$V_{GS} = \pm 20V, V_{DS} = 0V$			±100	nA

On Characteristics

$V_{GS(th)}$	Gate to Source Threshold Voltage	$V_{GS} = V_{DS}, I_{D} = -250 \mu A$	-1.0	-1.6	-3.0	V
$\frac{\Delta V_{GS(th)}}{\Delta T_J}$	Gate to Source Threshold Voltage Temperature Coefficient	I_D = -250 μ A, referenced to 25°C		5.3		mV/°C
		$V_{GS} = -10V, I_D = -10.5A$		11.0	13.0	
r _{DS(on)}	Static Drain to Source On Resistance	$V_{GS} = -4.5V, I_D = -8.4A$		15.2	19.0	mΩ
		$V_{GS} = -10V$, $I_D = -10.5A$, $T_J = 125$ °C		16.8	19.9	
9 _{FS}	Forward Transconductance	$V_{DD} = -5V, I_{D} = -10.5A$		37		S

Dynamic Characteristics

C _{iss}	Input Capacitance	V _{DS} = -20V, V _{GS} = 0V, f = 1MHz	2005	2670	pF
C _{oss}	Output Capacitance		355	475	pF
C _{rss}	Reverse Transfer Capacitance		190	285	pF
R_g	Gate Resistance	f = 1MHz	5		Ω

Switching Characteristics

t _{d(on)}	Turn-On Delay Time			10	20	ns
t _r	Rise Time	$V_{DD} = -20V, I_D = -10.5A,$		5	10	ns
t _{d(off)}	Turn-Off Delay Time	$V_{GS} = -10V, R_{GEN}$	= 6Ω	42	68	ns
t _f	Fall Time			12	22	ns
Q_{g}	Total Gate Charge	$V_{GS} = 0V \text{ to } -10V$		35	49	nC
Qg	Total Gate Charge	$V_{GS} = 0V \text{ to } -5V$	V _{DD} = -20V,	19	27	nC
Q _{gs}	Gate to Source Charge		I _D = -10.5A	6		nC
Q_{gd}	Gate to Drain "Miller" Charge			7		nC

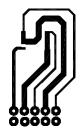
Drain-Source Diode Characteristics

V	V _{SD} Source to Drain Diode Forward Voltage	$V_{GS} = 0V, I_S = -10.5A$ (Note 2)	-0.8	-1.3	V
v SD		$V_{GS} = 0V, I_S = -2.1A$ (Note 2)	-0.7	-1.2	
t _{rr}	Reverse Recovery Time	I _F = -10.5A, di/dt = 100A/μs	26	42	ns
Q _{rr}	Reverse Recovery Charge	- I _F = -10.5A, αι/αι = 100A/μS	14	26	nC

^{1.} R_{θ,JA} is determined with the device mounted on a 1in² pad 2 oz copper pad on a 1.5 x 1.5 in. board of FR-4 material. R_{θ,JC} is guaranteed by design while R_{θ,CA} is determined by the user's board design.



a) 50°C/W when mounted on a 1in² pad of 2 oz copper.



b) 125°C/W when mounted on a minimum pad.

- 2. Pulse Test: Pulse Width < $300\mu\text{s},$ Duty cycle < 2.0%.
- 3. UIL condition: Starting T_J = 25°C, L = 3mH, I_{AS} = -14A, V_{DD} = -40V, V_{GS} = -10V.

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Typical Characteristics T_J = 25°C unless otherwise noted

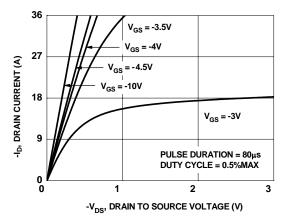


Figure 1. On-Region Characteristics

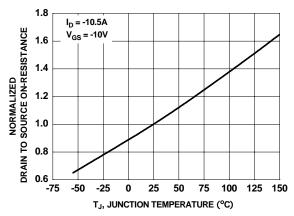


Figure 3. Normalized On-Resistance vs Junction Temperature

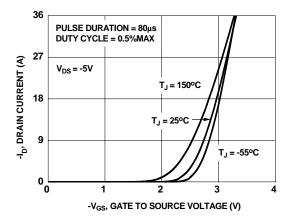


Figure 5. Transfer Characteristics

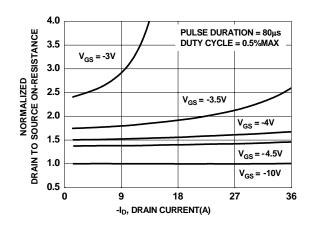


Figure 2. Normalized On-Resistance vs Drain Current and Gate Voltage

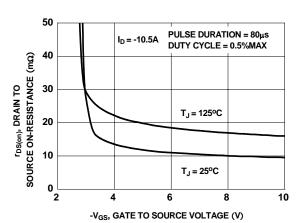


Figure 4. On-Resistance vs Gate to Source Voltage

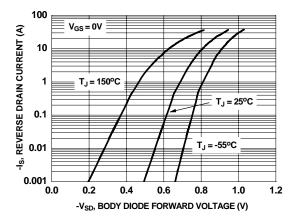


Figure 6. Source to Drain Diode Forward Voltage vs Source Current

Typical Characteristics T_J = 25°C unless otherwise noted

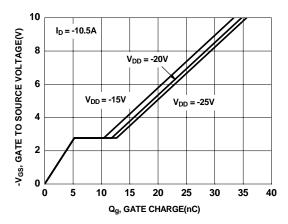


Figure 7. Gate Charge Characteristics

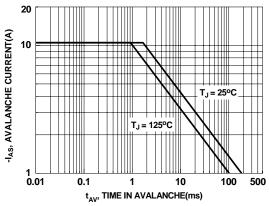


Figure 9. Unclamped Inductive Switching Capability

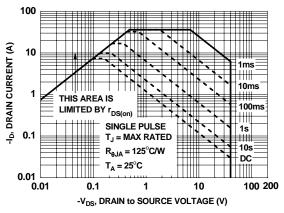


Figure 11. Forward Bias Safe Operating Area

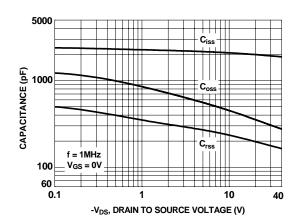


Figure 8. Capacitance vs Drain to Source Voltage

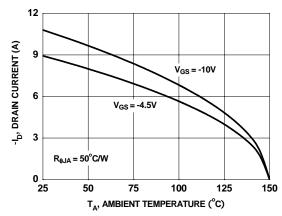


Figure 10. Maximum Continuous Drain Current vs Ambient Temperature

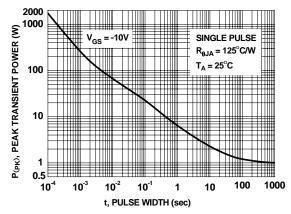


Figure 12. Single Pulse Maximum Power Dissipation

Typical Characteristics T_J = 25°C unless otherwise noted

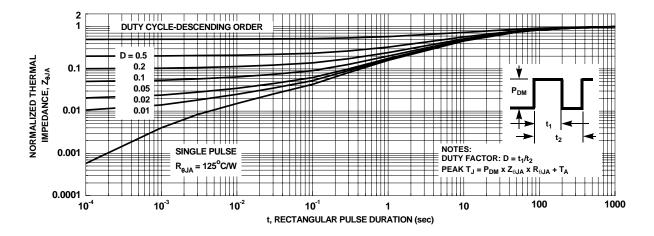
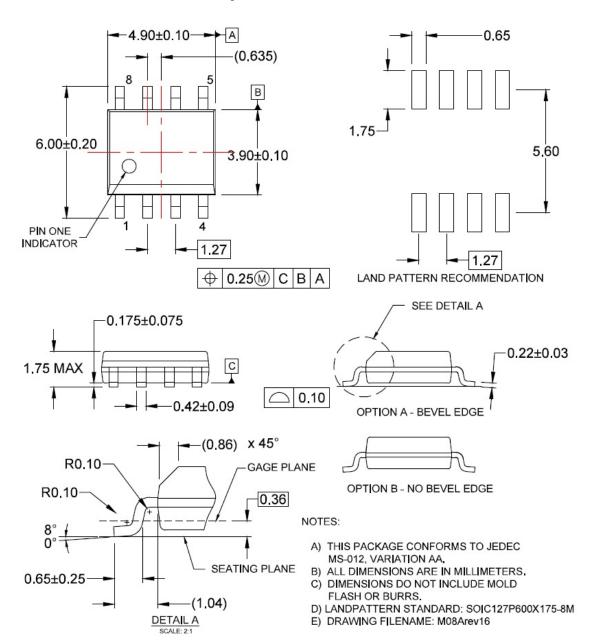


Figure 13. Transient Thermal Response Curve

Dimensional Outline and Pad Layout



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